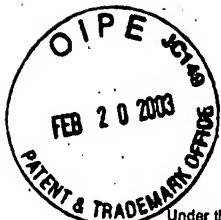


INFORMATION DISCLOSURE CITATION PTO-1449		ATTY. DOCKET NO.		SERIAL NO.			
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		APPLICANT Satayadev R. Patel, et al.					
		FILING DATE 12/03/01		GROUP 2812			
U.S. PATENT DOCUMENTS							
EXAMINER'S INITIALS	PATENT NO.	DATE	NAME	CLASS	SUBCLASS	FILING DATE	
NA	6,072,236	06/06/00	Akram, et al.				
NA	5,915,168	06/22/99	Salatino, et al.				
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OTHER DOCUMENTS (Including Author, Title, Date, Pertinent Pages, Etc.)							
NA	Tom Glenn, et al., PACKAGING MICROSCOPIC MACHINES, MACHINE DESIGN, December 7, 2000.						
	Balaji Sridharan, et al., POST-PACKAGING RELEASE A NEW CONCEPT FOR SURFACE MICROMACHINED DEVICES, Mechanical and Aerospace Engineering Department, 4 pgs.						
	U. Gosele, et al., WAFER BONDING FOR MICROSYSTEMS TECHNOLOGIES, Sensors and Actuators 74 (1999) Pgs 161-168.						
	Masao Segawa, et al., A CMOS IMAGE SENSOR MODULE APPLIED FOR A DIGITAL STILL CAMERA UTILIZING THE TAB ON GLASS (TOG) BONDING METHOD, IEEE TRANSACTIONS ON ADVANCED PACKAGING, VOL 22, NO. 2.						
NA	In-Byeong Kang, et al., THE APPLICATION OF ANISOTROPIC CONDUCTIVE FILMS FOR REALISATION OF INTERCONNECTS IN MICROMECHANICAL STRUCTURES, SPIE Vol. 3321, Pgs 233-238.						
	Sonja van der Groen, et al., CMOS COMPATIBLE WAFER SCALE ADHESIVE BONDING FOR CIRCUIT TRANSFER, International Conference on Solid- State Sensors and Actuators, Chicago, June 16-19, 1997, Pgs 629-632.						
	G. Blink, et al., WAFER BONDING WITH AN ADHESIVE COATING, Part of the SPIE Conference on Micromachined Devices and Components IV, Santa Clara, California, September 1998, Pgs 50-61.						
	Christine Kallmayer, et al., A NEW APPROACH TO VHIC SIZE PACKAGE USING MENISCUS SOLDERING AND FPC-BONDING, IEEE TRANSACTIONS ON COMPONENTS PACKAGING AND MANUFACTURING TECHNOLOGY-PART C, VOL. 21, NO. 1, JANUARY 1998, Pgs 51-56.						
	Joachim Kloeser, et al., LOW COST BUMPING BY STENCIL PRINTING: PROCESS QUALIFICATION FOR 200 UM PITCH, 1998 International Symposium on Microelectronics, 11 Pgs.						
	Michel M. Maharbiz, et al., BATCH MICROPACKAGING BY COMPRESSION-BONDED WAFER-WAFER TRANSFER, Microassembly Technologies, Inc, 8 Pgs.						

<p>no</p> <p>1</p> <p>NA</p>	Bharat Shivkumar, et al., MICRORIVETS FOR MEMS PACKAGING: CONCEPT, FABRICTION, AND STRENGTH TESTING, JOURNAL OF MICROELECTROMECHANICAL SYSTEMS, VOL. 6, NO.3, SEPTEMBER 1997, Pgs 217-224.
	Hideki Takagi, et al., ROOM TEMPERATURE SILICON WAFER DIRECT BONDING IN VACUUM BY Ar BEAM IRRADIATION, Mechanical Engineering Laboratory, AIST. MITI., 6 Pgs.
	Michael H. Beggans, et al., OPTICAL PRESSURE SENSOR HEAD FABRICATION USING ULTRA-THIN SILICON WAFER ANODIC BONDING, Part of the Symposium on Design, Test, and Microfabrication of MEMS and MOEMS, 10 Pgs.
	T.P Glenn, et al., DESIGNING MEMS INTO SYSTEMS: PACKAGING ISSUES, http://www.ecnmag.com , 4 Pgs.
EXAMINER <i>W. H. V. G.</i>	DATE CONSIDERED <i>5/4/04</i>

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Substitute for form 1449A/PTO		Complete if Known	
INFORMATION DISCLOSURE STATEMENT BY APPLICANT (use as many sheets as necessary)		Application Number	10/005,308
		Filing Date	December 3, 2001
		First Named Inventor	PATEL et al.
		Art Unit	2812
		Examiner Name	
Sheet	1	of	3
		Attorney Docket Number	P19-US

U.S. PATENT DOCUMENTS					
Examiner Initials	Cite No. 1	Document Number	Publication Date MM-DD-YYYY	Name of Patentee or Applicant of Cited Document	Pages, Columns, Lines, Where Relevant Passages or Relevant Figures Appear
		Number - Kind Code 2 (if known)			
[Signature]	AA	US- 4,178,077	12-11-1979	TE VELDE	[X]
	AB	US- 4,309,242	12-05-1982	TE VELDE	
	AC	US- 5,293,511	03-08-1994	PORADISH et al.	
	AD	US- 5,527,744	08-18-1996	MIGNARDI et al.	
	AE	US- 5,872,048	02-16-1999	KAERIYAMA et al.	
	AF	US- 5,963,289	10-05-1999	STEFANOV et al.	
	AG	US- 6,165,885	12-26-2000	GAYNES et al.	
	AH	US- 6,207,548 B1	03-27-2001	AKRAM et al.	
	AI	US- 6,232,150 B1	05-15-2001	LIN et al.	
	AJ	US- 6,252,229 B1	06-26-2001	HAYS et al.	
	AK	US- 6,287,940 B1	09-11-2001	COLE et al.	
	AL	US- 6,303,986 B1	10-16-2001	SHOOK	
	AM	US- 6,323,550 B1	11-27-2001	MARTIN et al.	
	AN	US- 6,353,492 B2	03-05-2002	McCLELLAND et al.	
	AO	US- 2001/0007372 A1	07-12-2001	AKRAM et al.	
	AP	US- 2001/0022207 A1	09-20-2001	HAYS et al.	
[Signature]	AQ	US- 2001/0034076 A1	10-25-2001	MARTIN	
	US-				
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FOREIGN PATENT DOCUMENTS					
Examiner Initials	Cite No. 1	Foreign Patent Document	Publication Date MM-DD-YYYY	Name of Patentee or Applicant of Cited Document	Pages, Columns, Lines, Where Relevant Passages or Relevant Figures Appear
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[Signature]	BA	EP-1097901-A2	05-09-2001	HA et al.	[X]
	BB	EP-1101730-A2	05-23-2001	WOOD et al.	
	BC	EP-1167281-A2	01-02-2002	KANG et al.	
	BD	WO-01/10718-A1	02-15-2001	GUANN-PYNG et al.	
	BE	WO-01/20671-A1	03-22-2001	XU et al.	
	BF	WO-02/12116-A2	02-14-2002	BROSNIHAN et al.	
	BG	WO-02/12116-A3	02-14-2002	BROSNIHAN et al.	
	BH	JP-2001129800-A	05-15-2001	MASAKI	
	BI	JP-2001144117-A	05-25-2001	OAKATTO et al.	
	BJ	JP-2001196484-A	07-19-2001	JU et al.	

Examiner Signature	[Signature]	Date Considered	5/4/04
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1 Applicant's unique citation designation number (optional). 2 See Kinds Codes of USPTO Patent Documents at www.uspto.gov or MPEP 901.04. 3 Enter Office that issued the document, by the two-letter code (WIPO Standard ST.3). 4 For Japanese patent documents, the indication of the year of the reign of the Emperor must precede the serial number of the patent document. 5 Kind of document by the appropriate symbols as indicated on the document under WIPO Standard ST. 16 if possible. 6 Applicant is to place a check mark here if English language Translation is attached.

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**INFORMATION DISCLOSURE
STATEMENT BY APPLICANT**

(use as many sheets as necessary)

Sheet 2 of 2

Complete if Known

Application Number 10/005,308
Filing Date December 3, 2001
First Named Inventor PATEL et al.
Group Art Unit 2812
Examiner Name
Attorney Docket Number P19-US

OTHER PRIOR ART - NON-PATENT LITERATURE DOCUMENTS

Examiner Initials ¹	Cite No. ¹	Include name of the author (in CAPITAL LETTERS), title of the article (when appropriate), title of the item (book, magazine, journal, serial, symposium, catalog, etc.), date, page(s), volume-issue number(s), publisher, city and/or country where published	T ²
[Signature]	CA	ESPINOSA et al., "Identification of Residual Stress State in an RF-MEMS Device", MTS Systems Corporation white paper (May 2000).	
	CB	FRANKA et al., "Solder Bump Technology: Present and Future", Semiconductor Fabtech (May 1995).	
	CC	GLENN et al., "Packaging Microscopic Machines", Machine Design (Dec. 7, 2000).	
	CD	HARSH et al., "Flip-Chip Assembly for Si-Based MEMS", Proceedings of the 1999 IEEE International Conference on Microelectromechanical Systems (MEMS '99), Orlando, FL (Jan. 17-21, 1999), pp. 273-278.	
	CE	IRWIN et al., "Quick Prototyping of Flip Chip Assembly with MEMS", University of Colorado at Boulder white paper (July 17, 2000).	
	CF	IRWIN et al., "Quick Prototyping of Flip-Chip Assembly with MEMS", portions of slide presentation from the NSF Center for Advanced Manufacturing and Packaging of Microwave, Optical and Digital Electronics at the University of Colorado at Boulder (1998).	
	CG	LEE et al., "High-Q Tunable Capacitors and Multi-way Switches Using MEMS for Millimeter-Wave Applications", portions of slide presentation from the NSF Center for Advanced Manufacturing and Packaging of Microwave, Optical and Digital Electronics at the University of Colorado at Boulder (Sept. 1998).	
	CH	LEE et al., "Use of Foundry Services to Prototype MEMS for Millimeter-wave Applications", portions of slide presentation from the NSF Center for Advanced Manufacturing and Packaging of Microwave, Optical and Digital Electronics at the University of Colorado at Boulder (1998).	
	CI	LUXBACHER, T., "Spray Coating for MEMS, Interconnect & Advanced Packaging Applications", HDI Magazine (May 1999) (abstract only).	
	CJ	MOORE, D., "Automation Requirements for Die Bonding Process", Electronics Engineer (July 2000).	
[Signature]	CK	TSAU, C., "Wafer-Level Packaging", MIT Microsystems Technology Laboratories Annual Report (May 2000), p. 49.	

Examiner Signature	[Signature]	Date Considered	5/14/04
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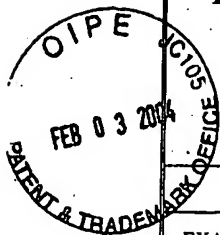
²Applicant's unique citation designation number (optional). ² Applicant is to place a check mark here if English language Translation is attached.

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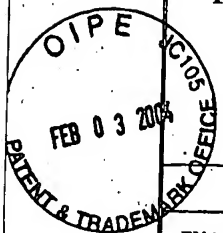
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				FILING DATE 12/03/01		GROUP 2812	
U.S. PATENT DOCUMENTS							
EXAMINER'S INITIALS	PATENT NO.	DATE	NAME	CLASS	SUBCLASS	FILING DATE	
MA	4,190,488	02/26/80	Winters	X	X	X	
	4,310,380	01/12/82	Flamn, et al.				
	4,498,953	02/12/85	Cook, et al.				
	4,740,410	04/26/88	Muller, et al.				
	4,789,426	12/06/88	Pipkin				
	5,330,301	07/19/94	Brancher				
	5,672,242	09/30/97	Jen				
	5,726,480	03/10/98	Pister				
	5,753,073	05/19/98	Jen				
	5,835,256	11/10/98	Huibers				
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	EP 0 878 824 A2	24.04.1998	EP			<input type="checkbox"/>	<input type="checkbox"/>
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MA	PCT-WO.00/52740, Filing date 6 March 2000.						
	PCT-WO.98/05605, Filing date 17 July 1997						
MA	PCT-WO 98/13856, Filing date 22 September 1997						
	PCT-WO 98/32163, Filing date 22 January 1998						
MA	PCT-WO 99/01887, Filing date 6 July 1998						
	PCT-WO 99/03313, Filing date 8 July 1998						
MA	PCT-WO 99/49506, Filing date 16 March 1999						
EXAMINER <i>Matthew C. [Signature]</i>				DATE CONSIDERED <i>5/4/04</i>			

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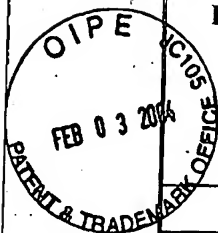
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			FILING DATE 12/03/01		GROUP 2812		
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	5,579,179	11/26/96	Ji, et al.				
	5,606,452	02/25/97	Min				
	5,637,517	06/10/97	Choi				
	5,677,785	10/14/97	Koo, et al.				
	5,690,839	11/25/97	Min				
	5,702,569	12/30/97	Park, et al.				
	5,706,122	01/06/98	Lim				
	5,735,026	04/07/98	Min				
	5,774,256	06/30/98	Min, et al.				
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NA	Kyu-Ho Hwang, et al., DESIGN AND FABRICATION OF THE THIN-FILM MICROMIRROR ARRAY-ACTUATED FOR LARGE PROJECTION DISPLAYS, November 1998, pp. S467-S470.						
	J.A. Walker, et al., A SILICON OPTICAL MODULATOR WITH 5 MHZ OPERATION FOR FIBER-IN-THE-LOOP APPLICATIONS, 1995, pp. 285-288.						
	C.G. Khan Malek, et al., ADHESION PROMOTION BETWEEN POLY(METHYLMETHACRYLATE) AND METALLIC SURFACES FOR LIGA EVALUATED BY SHEAR STRESS MEASUREMENTS, 1998, pp. 3543-3546.						
	C.H. Mastrangelo, ADHESION-RELATED FAILURE MECHANISMS IN MICROMECHANICAL DEVICES, 1997, pp. 223-238.						
	M.P. de Boer, et al., ADHESION, ADHESION HYSTERESIS AND FRICTION IN MEMS UNDER CONTROLLED HUMIDITY AMBIENTS, 1998, pp. 127-129.						
	Uthara Srinivasan, et al., ALKYLTRICHLOROSILANE-BASED SELF-ASSEMBLED MONOLAYER FILMS FOR STICTION REDUCTION IN SILICON MICROMACHINES, 1998, pp. 252-260.						
NA	Roya Maboudian, ANTI-STICTION COATING FOR SURFACE MICROMACHINES, 1998, pp. 108-113.						
EXAMINER: <i>[Signature]</i>			DATE CONSIDERED: 5/14/04				

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		GROUP 2812				
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<i>MS</i>	5,789,264	08/04/98	Chung			
	5,822,109	10/13/98	Jeon			
	5,834,163	11/10/98	Min, et al.			
	5,835,293	11/10/98	Min, et al.			
	5,841,569	11/24/98	Kim			
	5,859,724	01/12/99	Nam			
	5,877,889	03/02/99	Um, et al.			
	5,900,998	05/04/99	Kim, et al.			
	5,917,645	06/29/99	Min, et al.			
<i>MS</i>	5,920,422	07/06/99	Kim			
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<i>MS</i>	Michael R. Houston, et al., AMMONIM FLUORIDE ANTI-STICTION TREATMENTS FOR POLYSILICON MICROSTRUCTURES, 1995, pp. 210-214.					
	Roya Maboudian, et al., CRITICAL REVIEW: ADHESION IN SURFACE MICROMECHANICAL STRUCTURES, 1997, pp. 1-20.					
	Raj B. Apte, et al., DEFORMABLE GRATING LIGHT VALVES FOR HIGH RESOLUTION DISPLAYS, 1994, pp. 1-6.					
	P.F. Man, et al., ELIMINATION OF POST-RELEASE ADHESION IN MICROSTRUCTURES USING THIN CONFORMAL FLUOROCARBON FILMS, 1996, PP. 55-60.					
	Donna Cowell Senft, et al., FRICTION AND WEAR IN SURFACE MICROMACHINED TRIBOLOGICAL TEST DEVICES, PP. 31-38					
	P.R. Scheeper, et al., INVESTIGATION OF ATTRACTIVE FORCES BETWEEN PECVD SILICON NITRIDE MICROSTRUCTURES AND AN OXIDIZED SILICON SUBSTRATE, 1992, PP. 231-239.					
<i>MS</i>	Steven A. Henck, LUBRICATION OF DIGITAL MICROMIRROR DEVICES, 1997, pp. 239-247.					
EXAMINER <i>Walter M. G.</i>			DATE CONSIDERED <i>5/4/04</i>			

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INFORMATION DISCLOSURE CITATION		ATTY. DOCKET NO.		SERIAL NO.			
PTO-1449		P19-US		10/005,308			
SHEET 4 OF 6		APPLICANT Satayadev R. Patel, et al.		FILING DATE 12/03/01			
		GROUP 2812					
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	5,937,271	08/10/99	Min				
	5,991,064	11/23/99	Kim				
	6,104,525	08/15/00	Min				
	6,136,390	10/24/00	Park, et al.				
	6,203,715B1	03/20/01	Kim, et al.				
1/W	6,204,080B1	03/20/01	Hwang				
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1/B	Uthara Srinivasan, et al., LUBRICATION OF POLYSILICON MICROMECHANISMS WITH SELF-ASSEMBLED MONOLAYERS, 1998, pp. 156-161.						
	M.P. de Boer, et al., MEASURING AND MODELING ELECTROSTATIC ADHESION IN MICROMACHINES, 1997, pp. 229-232.						
	In-Ha Sung, et al., MICRO/NANO-TRIBOLOGICAL CHARACTERISTICS OF SELF-ASSEMBLED MONOLAYER AND ITS APPLICATION IN NANO-STRUCTURE FABRICATION, pp.808-818.						
	H. Zarrad, et al., OPTIMIZATION OF LUBRICANTS FOR SILICA MICROMOTORS, 1995, pp.598-600.						
	N.D. Shinn, et al., ORIGINS OF VISCOELASTIC DISSIPATION IN SELF-ASSEMBLED ORGANIC MONOLAYERS, 1998, pp. 169-175.						
	Keren Deng, et al., PERFORMANCE IMPACT OF MONOLAYER COATING OF POLYSILICON MICROMOTORS, 1995, pp. 368-373.						
1/B	C.Carraro, et al., SELECTIVE METALLIZATION OF SILICON MICROMECHANICAL DEVICES, 2002, pp. 2583-2588.						
EXAMINER <i>[Signature]</i>			DATE CONSIDERED 5/4/04				

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SHEET 5 OF 6		APPLICANT Satayadev R. Patel; et al.		FILING DATE 12/03/01		
		GROUP 2812				
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KS	Uthara Srinivasan et al., SELF-ASSEMBLED FLUOROCARBON FILM FOR ENHANCED STICTION REDUCTION, 1997, pp. 1399-1402.					
	Michael R. Houston, et al., SELF-ASSEMBLED MONOLAYER FILMS AS DURABLE ANTI-STICTION COATINGS FOR POLYSILICON MICROSTRUCTURES, 1996, pp. 42-47.					
	ZHAO Yapi, STICTION AND ANTI-STICTION IN MEMS AND NEMS, 2002, pp. 1-10.					
	Niels Tas, et al., STICTION IN SURFACE MICROMACHING, 1996, pp. 385-397.					
	Roya Maboudian, et al., STICTION REDUCTION PROCESSES FOR SURFACE MICROMACHINES, 1997, pp. 215-221.					
	K. Komvopoulos, SURFACE ENGINEERING AND MICROTRIBOLOGY FOR MICROELECTROMECHANICAL SYSTEMS, 1996, pp. 305-327.					
	K. Komvopoulos, SURFACE TEXTURING AND CHEMICAL TREATMENT METHODS FOR REDUCING HIGH ADHESION FORCES AT MICROMACHINE INTERFACES, 1998, pp. 106-122.					
	H. Zarrad, et al., THE USE OF LONG-CHAIN MOLECULES FOR THE LUBRICATION OF MICROMECHANISMS, 1993, pp. 222-224.					
	Bradley K. Smith, et al., THIN TEFLON-LIKE FILMS FOR MEMS: FILM PROPERTIES AND RELIABILITY STUDIES, 1998, pp. 114-124.					
	M. Lemieux, et al., TRIBOLOGICAL PROPERTIES OF CHEMICALLY MODIFIED MEMS, pp. 1181-1182					
	George M. Whitesides, UNCONVENTIONAL METHODS AND UNCONVENTIONAL MATERIALS FOR MICROFABRICATION, 1997, pp. 23-24.					
	S. Mubassar Ali, et al., USE OF THERMAL CYCLING TO REDUCE ADHESION OF OTS COATED MEMS CANTILEVERS, 2003, pp. 151-162					
W	Matthew G. Hankins, et al., VAPOR DEPOSITION OF AMINO-FUNCTIONALIZED SELF-ASSEMBLED MONOLAYERS ON MEMS, 2003, pp. 238-247.					
EXAMINER		DATE CONSIDERED		5/4/04		

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INFORMATION DISCLOSURE CITATION PTO-1449 SHEET 6 OF 6		ATTY. DOCKET NO. P19-US		SERIAL NO. 10/005,308			
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U.S. PATENT DOCUMENTS							
EXAMINER'S INITIALS	PATENT NO.	DATE	NAME	CLASS	SUBCLASS	FILING DATE	
FOREIGN PATENT DOCUMENTS							
EXAMINER'S INITIALS	PATENT NO.	DATE	COUNTRY	CLASS	SUBCLASS	TRANSLATION	
						YES	NO
						<input type="checkbox"/>	<input type="checkbox"/>
OTHER DOCUMENTS (Including Author, Title, Date, Pertinent Pages, Etc.)							
W	W. Robert Ashurst, et al., WAFER LEVEL ANTI-STICTION COATINGS FOR MEMS, 2003, pp.213-221.						
	Daniel Flamm, et al., XEF2 AND F-ATOM REACTIONS WITH SI: THEIR SIGNIFICANCE FOR PLASMA ETCHING, 1983, 5 pgs.						
U	Xenon Difluoride Etching System, 1999, 3 pgs.						
	U. Streller, et al., SELECTIVITY IN DRY ETCHING OF SI (100) WITH XEF2 AND VUV LIGHT, 1996, pp. 341-346.						
M	M. J. M. Vugts, et al., SI/XEF2 ETCHING: TEMPERATURE DEPENDENCE, 1996, pp. 2765-2774.						
	Xuan-Qi Wang, et al., GAS-PHASE SILICON ETCHING WITH BROMINE TRIFLUORIDE, 1997, pp. 1505-1508						
H	H. F. Winters, et al., THE ETCHING OF SILICON WITH XEF2 VAPOR, 1979, pp. 70-73.						
	Harold F. Winters, ETCH PRODUCTS FROM THE REACTION OF XEF2 WITH SIO2, SI3N4, SIC, AND SI IN THE PRESENCE OF ION BOMBARDMENT, 1983, pp. 927-931.						
X	Xenon Difluoride Isotropic Etch System, SEEING IS BELIEVING, STS, 4 pgs.						
EXAMINER		DATE CONSIDERED					

EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.